

Special Issue

Image Simulation in Remote Sensing

Message from the Guest Editor

This Special Issue aims to attract novel contributions covering topics of interest which include, but are not limited to the following:

- Image simulation at specific time when obstructed by weather and atmospheric effects
- Image simulation using images from manufactured sensors
- Image simulation under virtual atmospheric and environmental conditions
- Optical image simulation from SAR images
- Optical image simulation from optical images
- Multi-resolution image simulation
- Image conversion for multi-sensor images obtained from different acquisition methods
- Image simulation by spectral resolution

Both theoretical and experiment-oriented papers, including case studies and reviews, are encouraged for submission.

Guest Editor

Prof. Dr. Yang Dam Eo

Department of Advanced Technology Fusion, Konkuk University, Seoul 05029, Korea

Deadline for manuscript submissions

closed (10 June 2021)



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Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
appls@mdpi.com

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

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